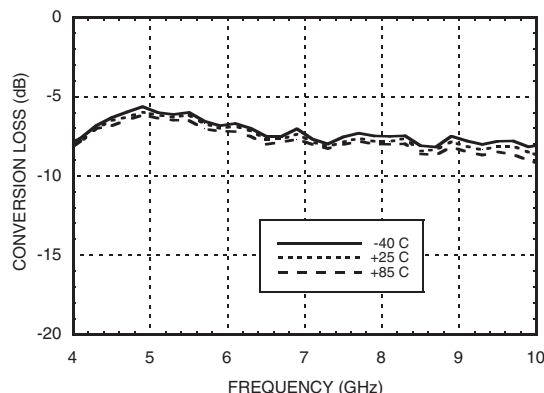


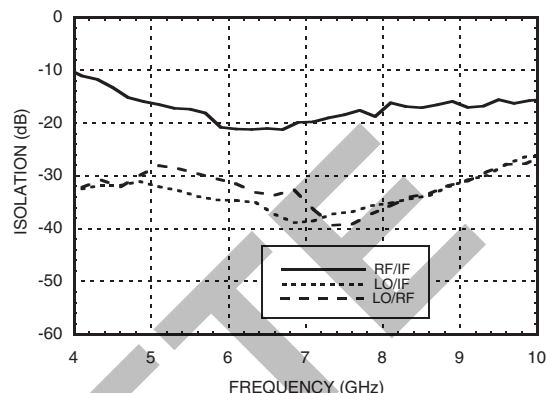


**GaAs MMIC SMT DOUBLE-
BALANCED MIXER, 4.5 - 9 GHz**

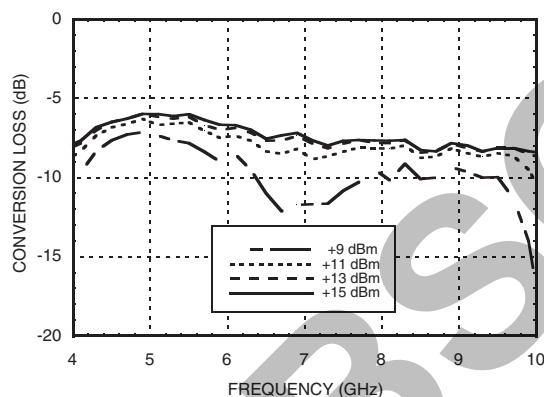
**Conversion Loss vs
Temperature @ LO = +13 dBm**



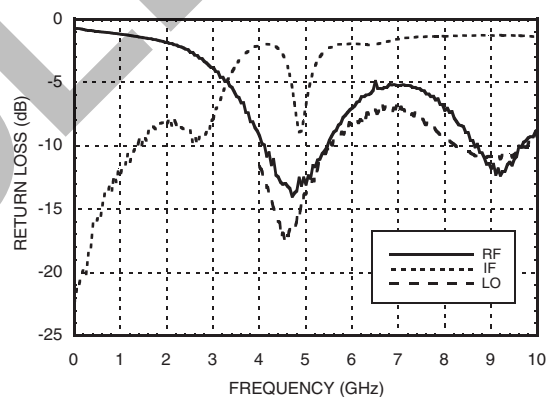
Isolation @ LO = +13 dBm



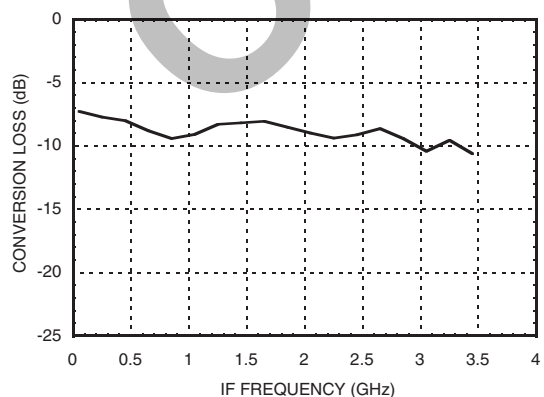
Conversion Loss vs. LO Drive



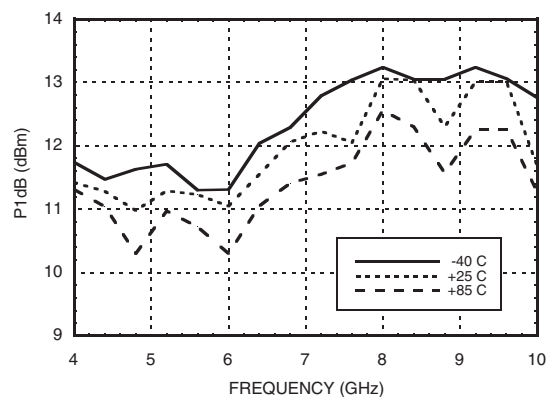
Return Loss @ LO = +13 dBm



IF Bandwidth @ LO = +13 dBm



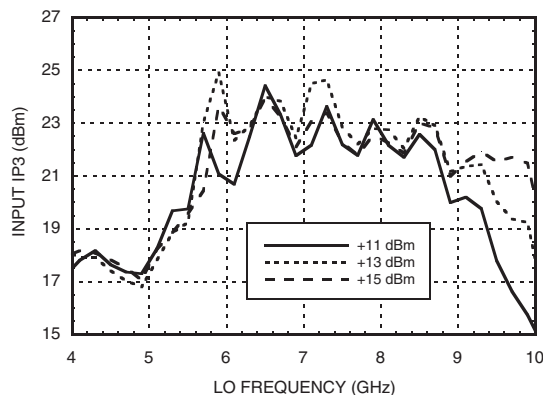
**P1dB vs.
Temperature LO = +13 dBm**



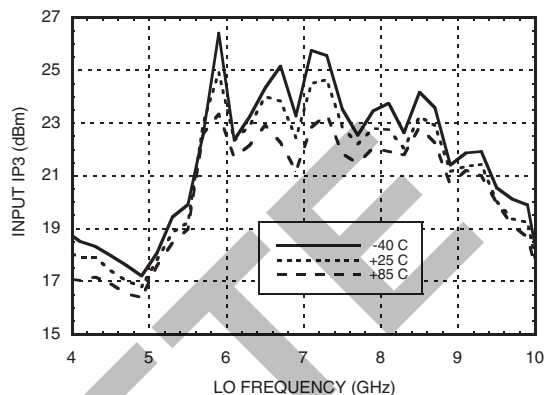


**GaAs MMIC SMT DOUBLE-
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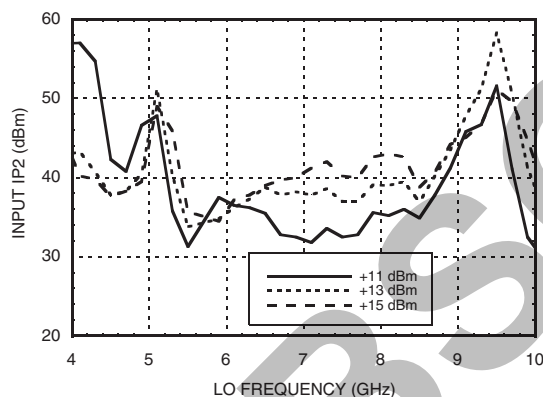
Input IP3 vs. LO Drive



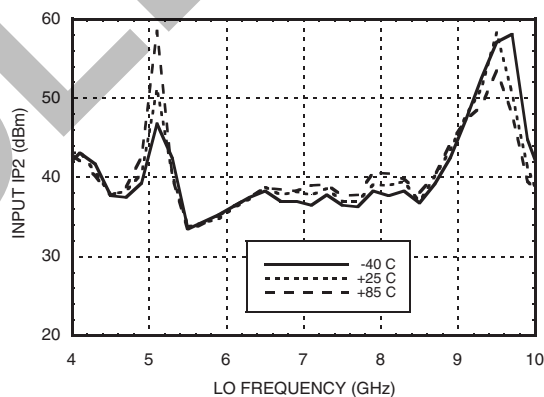
**Input IP3 vs.
Temperature @ LO = +13 dBm**



Input IP2 vs. Drive



**Input IP2 vs.
Temperature @ LO = +13 dBm**




**GaAs MMIC SMT DOUBLE-
BALANCED MIXER, 4.5 - 9 GHz**
MxN Spurious Outputs

mRF	nLO				
	0	1	2	3	4
0	xx	9	12	16	34
1	19	0	22	32	49
2	62	63	59	62	66
3	80	69	82	69	79
4	79	81	81	80	83

RF = 6 GHz @ -10 dBm
LO = 6.1 GHz @ +13 dBm
All values in dBc below the IF power level (-1RF + 1LO).

Harmonics of LO

LO Freq. (GHz)	nLO Spur at RF Port			
	1	2	3	4
4.0	31	22	32	58
5.0	32	21	30	47
6.0	40	28	28	49
7.0	32	35	53	48
8.0	27	40	57	55
9.0	22	52	48	xx

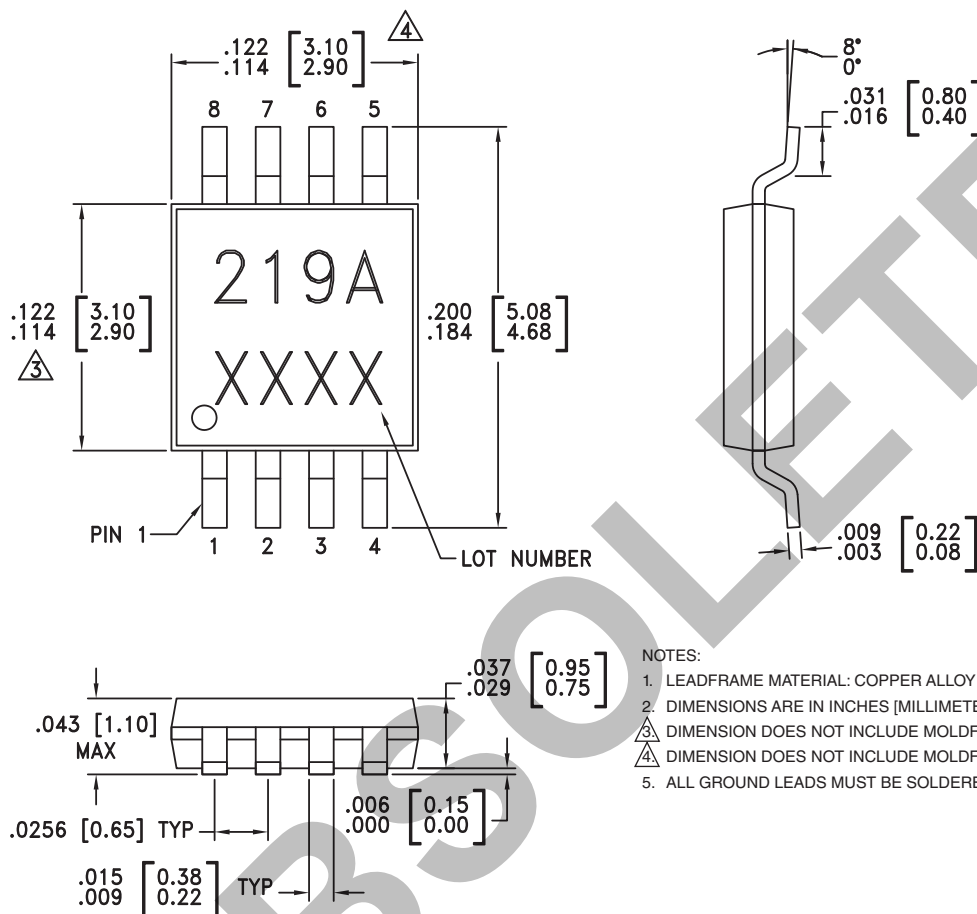
LO = +13 dBm
Values in dBc below input LO level measured at the RF port.

Absolute Maximum Ratings

RF / IF Input	+13 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**


**GaAs MMIC SMT DOUBLE-
BALANCED MIXER, 4.5 - 9 GHz**
Outline Drawing

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC219AMS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	219A XXXX
HMC219AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	219A XXXX

[1] Max peak reflow temperature of 235 °C

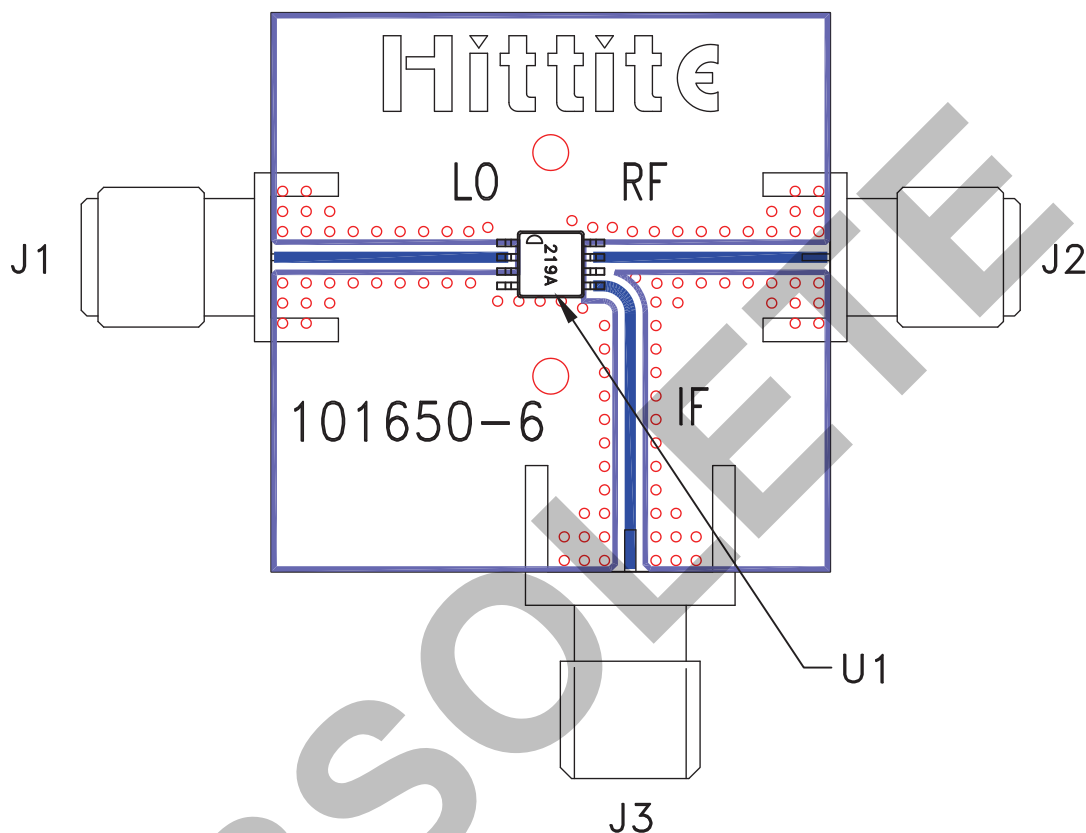
[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX



**GaAs MMIC SMT DOUBLE-
BALANCED MIXER, 4.5 - 9 GHz**

Evaluation Circuit Board



List of Materials for Evaluation PCB 103350 ^[1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC219AMS8 / HMC219AMS8E Mixer
PCB [2]	101650 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.